



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-04-19
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Giuseppe Vitali Palma	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
SMC30J12A	8HZH*TWU014M	A	64BA	2017-04-19
Amount	UoM	Unit type	ST ECOPACK Grade	
250.00	mg	Each	ECOPACK2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOJ	6.69-5.63-2.38	2	J bend	
Comment	SMC CLIP (SOD 15)			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

Query : California Prop65 list, dated 27th January 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.83	Back side Metal - Leadframe Metal	3308
Lead	6.96	Soft solder	27832

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	8ZH*TWU014M		250.0000			
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies (choose)	Other inorganic materials	9.224	mg	supplier	die	Silicon (Si)	7440-21-3		9.059	mg	982112	36236
				supplier	metallization	Aluminium (Al)	7429-90-5		0.026	mg	2819	104
				supplier	Passivation	Silicon Oxide	7631-86-9		0.034	mg	3686	136
				supplier	back side metallization	Aluminium (Al)	7429-90-5		0.035	mg	3794	140
				supplier	back side metallization	Gold (Au)	7440-57-5		0.012	mg	1301	48
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.058	mg	6288	232
Leadframe	Copper & its alloys	79.538	mg	supplier	alloy	Copper (Cu)	7440-50-8		78.691	mg	989338	314764
				supplier	alloy	CopperPhosphorous (CuP)	12517-41-8		0.078	mg	994	316
				supplier	metallization	Nickel (Ni)	7440-02-0		0.769	mg	9668	3076
Soft solder	Solder	7.561	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high met	6.958	mg	920249	27832
				supplier	solder	Silver (Ag)	7440-22-4		0.188	mg	24864	752
				supplier	solder	Tin (Sn)	7440-31-5		0.377	mg	49861	1508
				supplier	solder	Flux residue	Proprietary		0.038	mg	5026	152
				supplier	mold compound	Amorphous Silica	7631-86-9		82.011	mg	730995	328040
Encapsulation	Other Organic Materials	112.191	mg	supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		21.316	mg	189997	85264
				supplier	mold compound	Phenol resin	9003-35-4		3.366	mg	30002	13464
				supplier	mold compound	Bisphenol A-bisphenol A diglycidyle ether poly	25036-25-3		3.366	mg	30002	13464
				supplier	mold compound	Carbon black	1333-86-4		1.010	mg	9003	4040
				supplier	mold compound	Triphenylphosphine	603-35-0		0.785	mg	6997	3140
				supplier	mold compound	3-Mercaptopropyl trimethoxysilane	4420-74-0		0.337	mg	3004	1348
Connections coating	Solder	1.972	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.972	mg	1000000	7888
Clip	Copper & its alloys	39.514	mg	supplier	alloy	Copper (Cu)	7440-50-8		39.514	mg	1000000	158056